FUJITSU SEMICONDUCTOR
DATA SHEET

DS05-11125-1E

MEMORY

Unbuffered

4 M × 72 BIT SYNCHRONOUS DYNAMIC RAM DIMM

MB8504S072BZ-75/-102/-10

168-pin, 4 Clock, 2-bank, based on 2 M × 8 Bit SDRAMs with SPD

■ DESCRIPTION

The Fujitsu MB8504S072BZ is a fully decoded, CMOS Synchronous Dynamic Random Access Memory (SDRAM) Module consisting of eighteen MB81F16822B devices which organized as two banks of 2 M × 8 bits and a 2K-bit serial EEPROM on a 168-pin glass-epoxy substrate.

The MB8504S072BZ features a fully synchronous operation referenced to a positive edge clock whereby all operations are synchronized at a clock input which enables high performance and simple user interface coexistence.

The MB8504S072BZ is optimized for those applications requiring high speed, high performance and large memory storage, and high density memory organizations.
This module is ideally suited for workstations, PCs, laser printers, and other applications where a simple interface is needed.

■ PRODUCT LINE & FEATURES

Parameter		MB8504S072BZ-75	MB8504S072BZ-102	MB8504S072BZ-10
Clock Frequency		133 MHz max.	100 MHz max.	100 MHz max.
Burst Mode Cycle Time		7.5 ns max.	10 ns max.	10 ns max.
Output Valid from Clock		6 ns max. (CL = 3)	6 ns max. (CL = 2)	6 ns max. (CL = 3)
Power Dissipation	Two Banks Active	5735 mW max.	5184 mW max.	4536 mW max.
	Self Refresh Mode	25.92 mW max.		

- Unbuffered 168-pin DIMM Socket Type
  (Lead pitch: 1.27 mm)
- Conformed to JEDEC Standard (4 CLK)
- Organization: 4,194,304 words × 72 bits
- Memory: MB81F16822B (2 M × 8, 2-bank) × 18 pcs.
- 3.3 V ±0.3 V Supply Voltage
- All input/output LVTTL compatible
- Conformed to Intel PC/100 spec
- 4096 Refresh Cycle every 65.6 ms
- Auto and Self Refresh
- CKE Power Down Mode
- DQM Byte Masking (Read/Write)
- Serial Presence Detect (SPD) with Serial EEPROM:
  JEDEC Standard SPD Format
- Module size:
  1.35” (height) × 5.25” (length) × 0.157” (thickness)

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■ PACKAGE

168-pin plastic DIMM (socket type)

T.B.D.

(MDS-168P-P27)

Package and Ordering Information

– 168-pin DIMM, order as MB8504S072BZ-××DG (DG = Gold Pad)

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■ PIN ASSIGNMENTS

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
1	V_{SS}	29	$DQMB_1$	57	DQ_{18}	85	V_{SS}	113	$DQMB_5$	141	DQ_{50}
2	DQ_0	30	$\overline{CS}_0$	58	DQ_{19}	86	DQ_{32}	114	$\overline{CS}_1$	142	DQ_{51}
3	DQ_1	31	N.C.	59	V_{CC}	87	DQ_{33}	115	$\overline{RAS}$	143	V_{CC}
4	DQ_2	32	V_{SS}	60	DQ_{20}	88	DQ_{34}	116	V_{SS}	144	DQ_{52}
5	DQ_3	33	A_0	61	N.C.	89	DQ_{35}	117	A_1	145	N.C.
6	V_{CC}	34	A_2	62	N.C.	90	V_{CC}	118	A_3	146	N.C.
7	DQ_4	35	A_4	63	CKE_1	91	DQ_{36}	119	A_5	147	N.C.
8	DQ_5	36	A_6	64	V_{SS}	92	DQ_{37}	120	A_7	148	V_{SS}
9	DQ_6	37	A_8	65	DQ_{21}	93	DQ_{38}	121	A_9	149	DQ_{53}
10	DQ_7	38	A_{10}	66	DQ_{22}	94	DQ_{39}	122	BA_0	150	DQ_{54}
11	DQ_8	39	N.C.	67	DQ_{23}	95	DQ_{40}	123	N.C.	151	DQ_{55}
12	V_{SS}	40	V_{CC}	68	V_{SS}	96	V_{SS}	124	V_{CC}	152	V_{SS}
13	DQ_9	41	V_{CC}	69	DQ_{24}	97	DQ_{41}	125	CLK_1	153	DQ_{56}
14	DQ_{10}	42	CLK_0	70	DQ_{25}	98	DQ_{42}	126	N.C.	154	DQ_{57}
15	DQ_{11}	43	V_{SS}	71	DQ_{26}	99	DQ_{43}	127	V_{SS}	155	DQ_{58}
16	DQ_{12}	44	N.C.	72	DQ_{27}	100	DQ_{44}	128	CKE_0	156	DQ_{59}
17	DQ_{13}	45	$\overline{CS}_2$	73	V_{CC}	101	DQ_{45}	129	$\overline{CS}_3$	157	V_{CC}
18	V_{CC}	46	$DQMB_2$	74	DQ_{28}	102	V_{CC}	130	$DQMB_6$	158	DQ_{60}
19	DQ_{14}	47	$DQMB_3$	75	DQ_{29}	103	DQ_{46}	131	$DQMB_7$	159	DQ_{61}
20	DQ_{15}	48	N.C.	76	DQ_{30}	104	DQ_{47}	132	N.C.	160	DQ_{62}
21	CB_0	49	V_{CC}	77	DQ_{31}	105	CB_4	133	V_{CC}	161	DQ_{63}
22	CB_1	50	N.C.	78	V_{SS}	106	CB_5	134	N.C.	162	V_{SS}
23	V_{SS}	51	N.C.	79	CLK_2	107	V_{SS}	135	N.C.	163	CLK_3
24	N.C.	52	CB_2	80	N.C.	108	N.C.	136	CB_6	164	N.C.
25	N.C.	53	CB_3	81	N.C.	109	N.C.	137	CB_7	165	SA_0
26	V_{CC}	54	V_{SS}	82	SDA	110	V_{CC}	138	V_{SS}	166	SA_1
27	$\overline{WE}$	55	DQ_{16}	83	SCL	111	$\overline{CAS}$	139	DQ_{48}	167	SA_2
28	$DQMB_0$	56	DQ_{17}	84	V_{CC}	112	$DQMB_4$	140	DQ_{49}	168	V_{CC}

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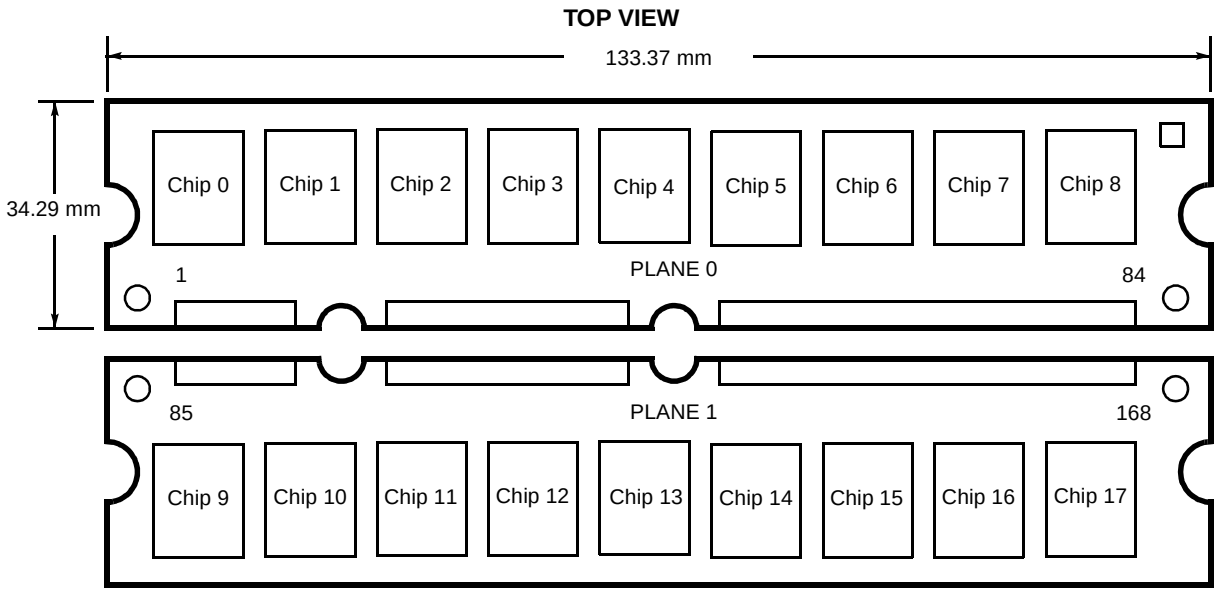

(MDS-168P-27)

■ PIN DESCRIPTIONS

Symbol	I/O	Function	Symbol	I/O	Function
A_0 to A_{10}, BA_0	I	Address Input	DQ_0 to DQ_{63}	I/O	Data Input/Data Output
$\overline{RAS}$	I	Row Address Strobe	CB_0 to CB_7	I/O	ECC Data Input/Output
$\overline{CAS}$	I	Column Address Strobe	V_{CC}	—	Power Supply (+3.3 V)
$\overline{WE}$	I	Write Enable	V_{SS}	—	Ground (0 V)
$DQMB_0$ to $DQMB_7$	I	Data (DQ) Mask	N.C.	—	No Connection
CLK_0 to CLK_3	I	Clock Input	SA_0 to SA_2	I	Serial PD Address Input
CKE_0, CKE_1	I	Clock Enable	SCL	I	Serial PD Clock
$\overline{CS_0}$ to $\overline{CS_3}$	I	Chip Select	SDA	I/O	Serial PD Address/Data Input/Output

■ SERIAL-PD INFORMATION

Byte	Function Described		Hex Value		
			-75	-102	-10
0	Defines Number of Bytes Written into Serial Memory at Module Manufacture	128 Byte	80h	80h	80h
1	Total Number of Bytes of SPD Memory Device	256 Byte	08h	08h	08h
2	Fundamental Memory Type	SDRAM	04h	04h	04h
3	Number of Row Addresses	11	0Bh	0Bh	0Bh
4	Number of Column Addresses	9	09h	09h	09h
5	Number of Module Banks	2 bank	02h	02h	02h
6	Data Width	72 bit	48h	48h	48h
7	Data Width (Continuation)	+0	00h	00h	00h
8	Interface Type	LVTTL	01h	01h	01h
9	SDRAM Cycle Time (Highest CAS Latency)	7.5/10/10 ns	75h	A0h	A0h
10	SDRAM Access from Clock (Highest CAS Latency)	6/6/6 ns	60h	60h	60h
11	DIMM Configuration Type	ECC	02h	02h	02h
12	Refresh Rate/Type	Self, Normal	80h	80h	80h
13	Primary SDRAM Width	×8	08h	08h	08h
14	Error Checking SDRAM Width	×8	08h	08h	08h
15	Minimum Clock Delay for Back to Back Random Column Addresses	1 Cycle	01h	01h	01h
16	Burst Lengths Supported	1, 2, 4, 8, Page	8Fh	8Fh	8Fh
17	Number of Banks on Each SDRAM Device	2 bank	02h	02h	02h
18	CAS Latency	2, 3	06h	06h	06h
19	CS Latency	0	01h	01h	01h
20	Write Latency	0	01h	01h	01h
21	SDRAM Module Attributes	UN-buffer	00h	00h	00h
22	SDRAM Device Attributes	*1	06h	06h	06h
23	SDRAM Cycle Time (2nd. Highest CAS Latency)	11.5/10/15 ns	B5h	A0h	A5h
24	SDRAM Access from Clock (2nd. Highest CAS Latency)	7/6/8 ns	70h	60h	80h
25	SDRAM Cycle Time (3rd. Highest CAS Latency)	No Support	00h	00h	00h
26	SDRAM Access from Clock (3rd. Highest CAS Latency)	No Support	00h	00h	00h
27	Minimum Row Precharge Time (t_{RP})	22.5/20/30 ns	17h	14h	1Eh
28	Row Activate to Row Activate Minimum (t_{RRD})	15/20/20 ns	0Fh	14h	14h
29	$\overline{RAS}$ to $\overline{CAS}$ Delay Min. (t_{RCD})	22.5/20/30 ns	17h	14h	1Eh
30	Minimum RAS Pulse Width	45/50/50 ns	2Dh	32h	32h
31	Module Bank Density	16 MByte	04h	04h	04h
32 to 61	Unused Storage Locations	—	00h	00h	00h
62	SPD Data Revision Code	1	01h	01h	01h
63	Checksum for Byte 0 to 62	*2	86h	C0h	C9h
64 to 98	Manufacturer's Information: Unused Storage	—	00h	00h	00h
99 to 125	Vendor Specific Data: Unused Storage	—	00h	00h	00h
126	Intel Specification Frequency	66 MHz	66h	66h	66h
127	Intel Specification CAS Latency Support	CL = 2	02h	02h	02h
128+	Unused Storage Locations	—	—	—	—

Note: Any write operation must NOT be executed into the addresses of Byte 0 to Byte 127. Some or all data stored into Byte 0 to Byte 127 may be broken.

*1. Byte 22: SDRAM Device Attributes

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TBD	TBD	Upper V_{CC} tolerance	Lower V_{CC} tolerance	Supports Write 1 /Read Burst	Supports Precharge All	Supports Auto-Precharge	Supports Early $\overline{RAS}$ Precharge
0	0	0	0	0	1	1	0

*2. byte 63: Checksum for Byte 0 to 62
This byte is the checksum for bytes 0 through 62. This byte contains the value of the low 8-bits of the arithmetic sum of bytes 0 through 62.

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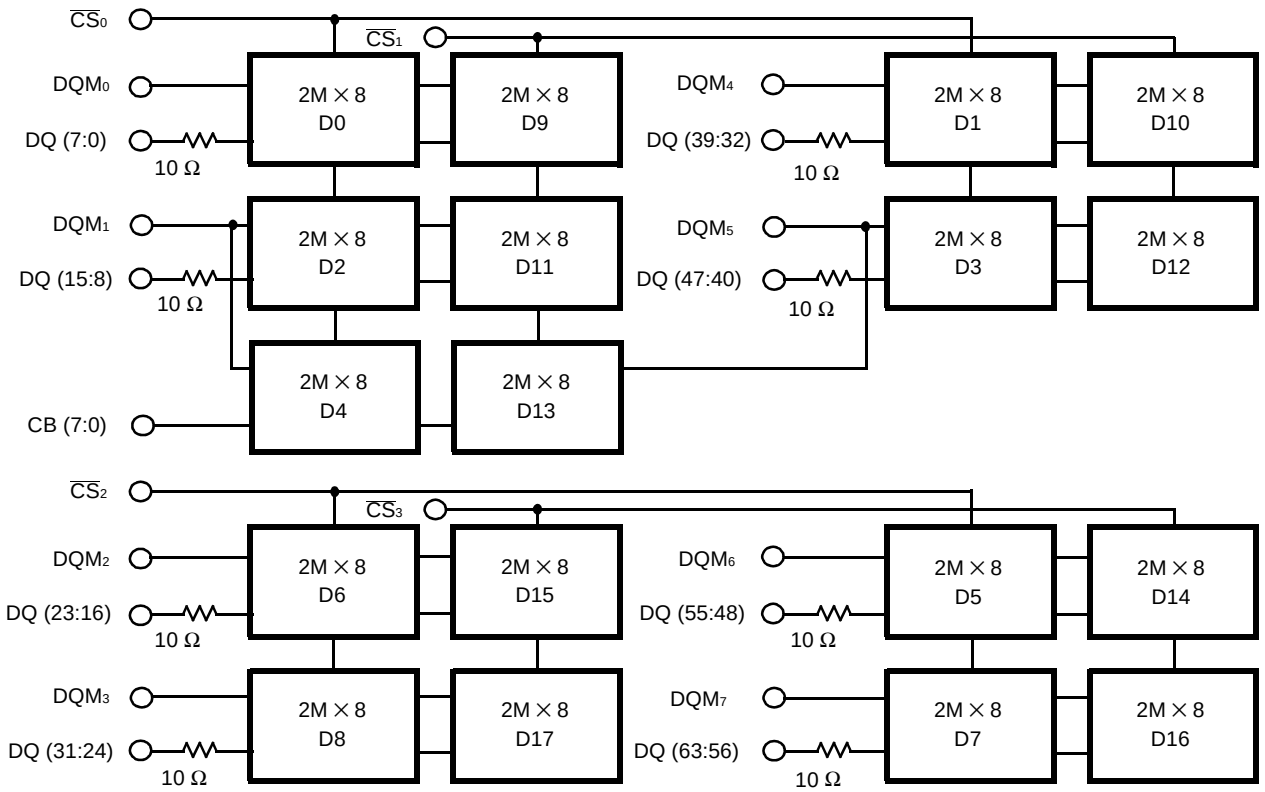
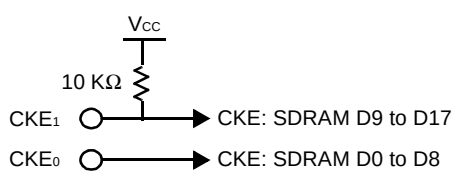
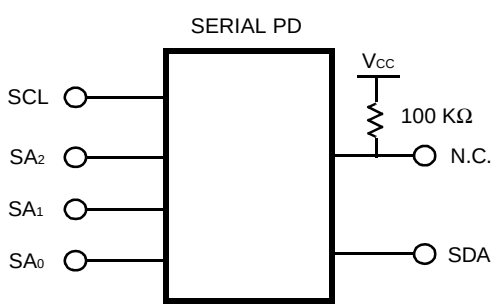
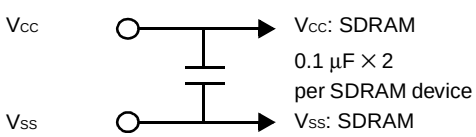
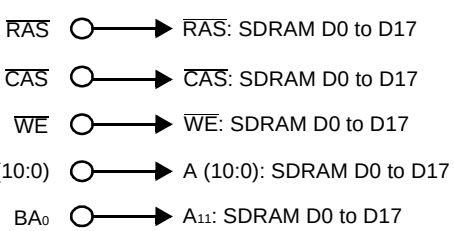
BLOCK DIAGRAM

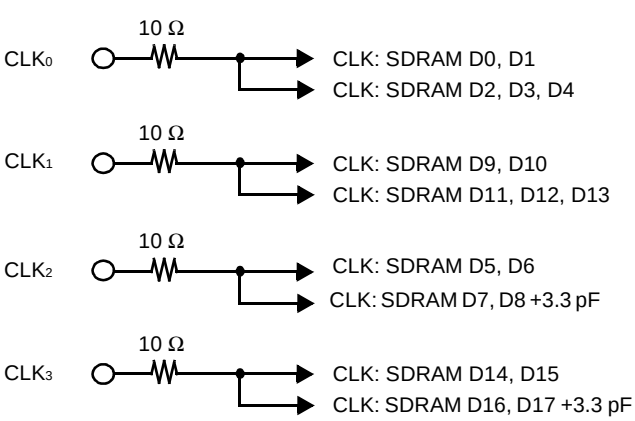












■ ABSOLUTE MAXIMUM RATINGS (See WARNING)

Parameter	Symbol	Value		Unit
		Min.	Max.	
Supply Voltage*	V_{CC}	–0.5	+4.6	V
Input Voltage*	V_{IN}	–0.5	+4.6	V
Output Voltage*	V_{OUT}	–0.5	+4.6	V
Storage Temperature	T_{STG}	–55	+125	°C
Power Dissipation	P_D	—	23.4	W
Output Current (D.C.)	I_{OUT}	–50	+50	mA

* : Voltages referenced to V_{SS} (= 0 V)

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Notes	Symbol	Value			Unit
			Min.	Typ.	Max.	
Supply Voltage		V_{CC}	3.0	3.3	3.6	V
		V_{SS}	0	0	0	V
Input High Voltage, All Inputs	*1	V_{IH}	2.0	—	V_{CC} +0.5	V
Input Low Voltage, All Inputs	*2	V_{IL}	–0.5	—	0.8	V
Ambient Temperature		T_A	0	—	+70	°C

*1. Overshoot limit: V_{IH} (max.) = TBD

*2. Undershoot limit: V_{IL} (min) = –1.5 V AC (Pulse Width ≤ 5 ns)

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

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■ CAPACITANCE

(V_{CC} = +3.3 V, f = 1 MHz, T_A = +25°C)

Parameter		Symbol	Value		Unit
			Min.	Max.	
Input Capacitance	A_0 to A_{10}, BA_0	C_{IN1}	—	89	pF
	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$	C_{IN2}	—	99	pF
	$\overline{CS}_0$ to $\overline{CS}_3$	C_{IN3}	—	36	pF
	CKE_0, CKE_1	C_{IN4}	—	64	pF
	CLK_0 to CLK_3	C_{IN5}	—	45	pF
	$DQMB_0$ to $DQMB_7$	C_{IN6}	—	24	pF
	SCL	C_{SCL}	—	6	pF
	SA_0, SA_1, SA_2	C_{SA}	—	7	pF
Input/Output Capacitance	SDA	C_{SDA}	—	6	pF
	DQ_0 to DQ_{63}	C_{DQ}	—	19	pF
	CB_0 to CB_7	C_{CB}	—	19	pF

■ DC CHARACTERISTICS

(At recommended operating conditions unless otherwise noted.)

Parameter	Notes		Symbol	Condition	Value		Unit
					Min.	Max.	
Operating Current (Average Power Supply Current)	*1	MB8504S072BZ-75	I_{CC1S}	Burst Length = 4, t_{RC} = min for BL = 4, t_{CK} = min, One Bank Active, Outputs Open, 0 V ≤ V_{IN} ≤ V_{CC}	—	1143	mA
		MB8504S072BZ-102				1080	mA
		MB8504S072BZ-10				900	mA
		MB8504S072BZ-75	I_{CC1D}	Burst Length = 4, t_{RC} = min for BL = 4, t_{CK} = min, All Banks Active, Outputs Open, 0 V ≤ V_{IN} ≤ V_{CC}	—	1593	mA
		MB8504S072BZ-102				1440	mA
		MB8504S072BZ-10				1260	mA
Precharge Standby Current (Power Supply Current)			I_{CC2P}	CKE = V_{IL}, t_{CK} = min, All Banks Idle, Power Down Mode, 0 V ≤ V_{IN} ≤ V_{CC}	—	7.2	mA
			I_{CC2PS}	CKE = V_{IL}, CLK = V_{IH} or V_{IL}, All Banks Idle, Power Down Mode, 0 V ≤ V_{IN} ≤ V_{CC}	—	7.2	mA
	*1	MB8504S072BZ-75	I_{CC2N}	CKE = V_{IH}, t_{CK} = min, All Banks Idle, 0 V ≤ V_{IN} ≤ V_{CC}	—	486	mA
		MB8504S072BZ-102				360	
		MB8504S072BZ-10				360	
			I_{CC2NS}	CKE = V_{IH}, CLK = V_{IH} or V_{IL}, All Banks Idle, Input Signal are Stable, 0 V ≤ V_{IN} ≤ V_{CC}	—	270	mA
Active Standby Current (Power Supply Current)			I_{CC3P}	CKE = V_{IL}, t_{CK} = min, Any Bank Active, 0 V ≤ V_{IN} ≤ V_{CC}	—	90	mA
			I_{CC3PS}	CKE = V_{IL}, CLK = V_{IH} or V_{IL}, Any Bank Active, 0 V ≤ V_{IN} ≤ V_{CC}	—	54	mA
	*1	MB8504S072BZ-75	I_{CC3N}	CKE = V_{IH}, t_{CK} = min, Any Bank Active, 0 V ≤ V_{IN} ≤ V_{CC}	—	972	mA
		MB8504S072BZ-102				720	
		MB8504S072BZ-10				720	
			I_{CC3NS}	CKE = V_{IH}, CLK = V_{IH} or V_{IL}, Any Bank Active, 0 V ≤ V_{IN} ≤ V_{CC}	—	450	mA

(Continued)

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(Continued)

Parameter	Notes		Symbol	Condition	Value		Unit
					Min.	Max.	
Burst Mode Current (Average Power Supply Current)	*1	MB8504S072BZ-75	I_{CC4}	t_{CK} = min, Gapless data, Burst Length = 4, Outputs open, Multiple-banks Active, 0 V ≤ V_{IN} ≤ V_{CC}	—	1593	mA
		MB8504S072BZ-102			—	1260	mA
		MB8504S072BZ-10			—	1260	mA
Auto-refresh Current (Average Power Supply Current)	*1	MB8504S072BZ-75	I_{CC5}	Auto Refresh, t_{CK} = min, t_{RC} = min, 0 V ≤ V_{IN} ≤ V_{CC}	—	1800	mA
		MB8504S072BZ-102			—	1440	mA
		MB8504S072BZ-10			—	1440	mA
Self-refresh Current (Average Power Supply Current)			I_{CC6}	Self-refresh, t_{CK} = min, CKE ≤ 0.2 V, 0 V ≤ V_{IN} ≤ V_{CC}	—	7.2	mA
			I_{CC6A}	Asynchronous Self-refresh (by CLK stop), CKE ≤ 0.2 V, CLK = V_{IL}, 0 V ≤ V_{IN} ≤ V_{CC}	—	7.2	mA
Input Leakage Current (All Inputs)			I_{LI}	0 V ≤ V_{IN} ≤ V_{CC} All other pins not under test = 0 V, 3.0 V ≤ V_{CC} ≤ 3.6 V	–90	90	µA
Output Leakage Current			I_{LO}	Output is disabled (Hi-Z) 0 V ≤ V_{IN} ≤ V_{CC} 3.0 V ≤ V_{CC} ≤ 3.6 V	–20	20	µA
LVTTL Output High Voltage	*2		V_{OH}	I_{OH} = –2.0 mA	2.4	—	V
LVTTL Output Low Voltage	*2		V_{OL}	I_{OL} = +2.0 mA	—	0.4	V

Notes: *1. I_{CC} depends on the output termination, load conditions, clock cycle rate and signal clock rate. The specified values are obtained with the output open and no termination register.

*2. Voltages referenced to V_{SS} (= 0 V)

*3. An initial pause (DESL on NOP) of 200 µs is required after power-on followed by a minimum of eight Auto-refresh cycles.

*4. Values except I_{CC1S}, I_{CC1D} and I_{CC4} are for when one side of the double-sided module is in standby mode (I_{CC2N})and the other side has two banks active in burst mode.

*5. DC characteristics is the Serial PD standby state (V_{IN} = GND or V_{CC}).

■ AC CHARACTERISTICS

(1) BASE CHARACTERISTICS
(At recommended operating conditions unless otherwise noted.)

No.	Parameter	Notes		Symbol	MB8504S072BZ -75		MB8504S072BZ -102		MB8504S072BZ -10		Unit
					Min.	Max.	Min.	Max.	Min.	Max.	
1	Clock Period		CL = 3	t_{CK3}	7.5	—	10	—	10	—	ns
			CL = 2	t_{CK2}	11.5	—	10	—	15	—	
2	Clock High Time			t_{CH}	2.5	—	3	—	3	—	ns
3	Clock Low Time			t_{CL}	2.5	—	3	—	3	—	ns
4	Input Setup Time			t_{SI}	2	—	2	—	2	—	ns
5	Input Hold Time			t_{HI}	1	—	1	—	1	—	ns
6	Output Valid from Clock (t_{CLK} = min)	*1, *2	CL = 3	t_{AC3}	—	6	—	6	—	6	ns
			CL = 2	t_{AC2}	—	7	—	6	—	8	
7	Output in Low-Z			t_{LZ}	0	—	0	—	0	—	ns
8	Output in High-Z	*3	CL = 3	t_{HZ3}	2	6	3	6	3	6	ns
			CL = 2	t_{HZ2}	3	7	3	6	3	8	
9	Output Hold Time		CL = 3	t_{OH}	2	—	3	—	3	—	ns
			CL = 2		3	—	3	—	3	—	
10	Time between Auto-Refresh Command Interval			t_{REFI}	—	15.6	—	15.6	—	15.6	µs
11	Time between Refresh			t_{REF}	—	65.6	—	65.6	—	65.6	ms
12	CKE Low (or CLK Low) Hold Time for Asynchronous Self-Refresh Entry			t_{ASE}	100	—	100	—	100	—	µs
13	Transition Time			t_T	0.5	2	0.5	2	0.5	2	ns
14	CKE Setup Time for Power Down Exit Time			t_{CKSP}	3	—	3	—	3	—	ns

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(2) BASE VALUES FOR CLOCK COUNT/LATENCY

No.	Parameter	Notes	Symbol	MB8504S072BZ-75		MB8504S072BZ-102		MB8504S072BZ-10		Unit
				Min.	Max.	Min.	Max.	Min.	Max.	
1	$\overline{RAS}$ Cycle Time	*4	t_{RC}	67.5	—	70	—	80	—	ns
2	$\overline{RAS}$ Precharge Time		t_{RP}	22.5	—	20	—	30	—	ns
3	$\overline{RAS}$ Active Time		t_{RAS}	45	100000	50	100000	50	100000	ns
4	$\overline{RAS}$ to $\overline{CAS}$ Delay Time	*5	t_{RCD}	22.5	—	20	—	30	—	ns
5	Write Recovery Time		t_{WR}	7.5	—	10	—	10	—	ns
6	Data-in to Precharge Lead Time		t_{DPL}	7.5	—	10	—	10	—	ns
7	Data-in to Active/Refresh Command Period	CL = 3	t_{DAL3}	2 cyc + t_{RP}	—	2 cyc + t_{RP}	—	2 cyc + t_{RP}	—	ns
		CL = 2	t_{DAL2}	1 cyc + t_{RP}	—	1 cyc + t_{RP}	—	1 cyc + t_{RP}	—	
8	Mode Register Set Cycle Time		t_{RSC}	15	—	20	—	20	—	ns
9	$\overline{RAS}$ to $\overline{RAS}$ Bank Active Delay Time		t_{RRD}	15	—	20	—	20	—	ns

(3) CLOCK COUNT FORMULA (*6)

$$\text{Clock} \geq \frac{\text{Base Value}}{\text{Clock Period}} \quad \text{(Round off a whole number)}$$

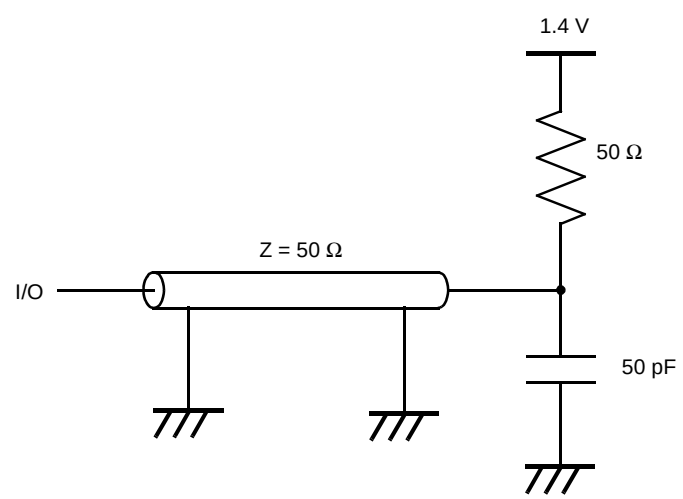
(4) LATENCY (The latency values on these parameters are fixed regardless of clock period.)

No.	Parameter		Symbol	MB8504S072BZ-75	MB8504S072BZ-102	MB8504S072BZ-10	Unit
1	CKE to Clock Disable		l_{CKE}	1	1	1	Cycle
2	DQM to Output in High-Z		l_{DQZ}	2	2	2	Cycle
3	DQM to Input Data Delay		l_{DQD}	0	0	0	Cycle
4	Last Output to Write Command Delay		l_{OWD}	2	2	2	Cycle
5	Write Command to Input Data Delay		l_{DWD}	0	0	0	Cycle
6	Precharge to Output in High-Z Delay	CL = 3	l_{ROH3}	3	3	3	Cycle
		CL = 2	l_{ROH2}	2	2	2	
7	Burst Stop Command to Output in High-Z Delay	CL = 3	l_{BSH3}	3	3	3	Cycle
		CL = 2	l_{BSH2}	2	2	2	
8	$\overline{CAS}$ to $\overline{CAS}$ Delay (min)		l_{CCD}	1	1	1	Cycle
9	$\overline{CAS}$ Bank Delay (min)		l_{CBD}	1	1	1	Cycle

Notes: *1. Assumes t_{RCD} is satisfied.
*2. t_{AC} also specifies the access time at burst mode except for first access.
*3. Specified where output buffer is no longer driven.
*4. Actual clock count of t_{RC} (I_{RC}) will be sum of clock count of t_{RAS} (I_{RAS}) and t_{RP} (I_{RP}).
*5. Operation within the t_{RCD} (min) ensures that access time is determined by t_{RCD} (min) +t_{AC} (max) ; if t_{RCD} is greater than the specified t_{RCD} (min), access time is determined by t_{AC}.
*6. All base values are measured from the clock edge at the command input to the clock edge for the next command input.
All clock counts are calculated by a simple formula:
clock count equals base value divided by clock period (round off to a whole number).
*7. An initial pause (DESL on NOP) of 200 µs is required after power-up followed by a minimum of eight Auto-refresh cycles.
*8. 1.4 V or V_{REF} is the reference level for measuring timing of signals.
Transition times are measured between V_{IH} (min) and V_{IL} (max).
*9. AC characteristics assume t_T = 1 ns and 50 pF of capacitive load.

*Source: See MB81F16822B Data Sheet for details on the electricals.

■ AC OPERATING TEST CONDITION (Example of AC Test Load Circuit)



■ SERIAL PRESENCE DETECT(SPD) FUNCTION

1. PIN DESCRIPTIONS

SCL (Serial Clock)

SCL input is used to clock all data input/output of SPD

SDA (Serial Data)

SDA is a common pin used for all data input/output of SPD. The SDA pull-up resistor is required due to the open-drain output.

SA_0, SA_1, SA_2 (Address)

Address inputs are used to set the least significant three bits of the eight bits slave address. The address inputs must be fixed to select a particular module and the fixed address of each module must be different each other.

2. SPD OPERATIONS

CLOCK and DATA CONVENTION

Data states on the SDA can change only during SC L= Low. SDA state changes during SCL = High are indicated start and stop conditions. Refer to Fig. 1 below.

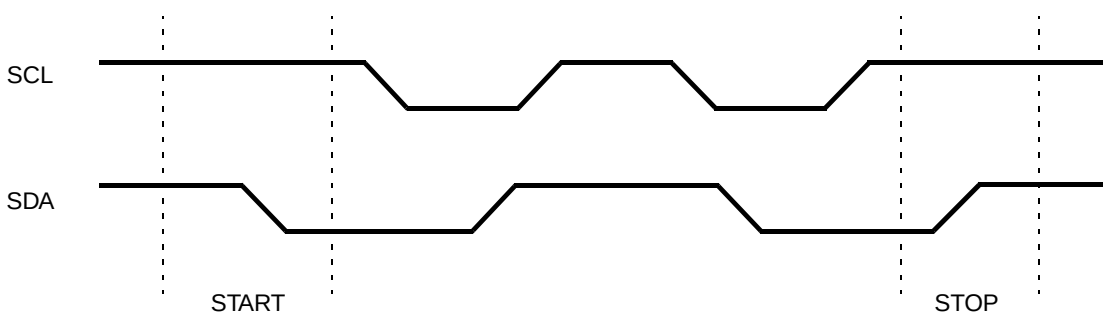
START CONDITION

All commands are preceded by a start condition, which is a transition of SDA state from High to Low when SCL = High. SPD will not respond to any command until this condition has been met.

STOP CONDITION

All read or write operation must be terminated by a stop condition, which is a transition of SDA state from Low to High when SCL = High. The stop condition is also used to make the SPD into the state of standby power mode after a read sequence.

Fig. 1 – START AND STOP CONDITIONS



START = High to Low transition of SDA state when SCL is High

STOP = Low to High transition of SDA state when SCL is High

ACKNOWLEDGE

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle the receiver will put the SDA line to Low in order to acknowledge that it received the eight bits of data.

The SPD will respond with an acknowledge when it received the start condition followed by slave address issued by master.

In the read operation, the SPD will transmit eight bits of data, release the SDA line and monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is issued by master, the SPD will continue to transmit data. If an acknowledge is not detected, the SPD will terminated further data transmissions. The master must then issue a stop condition to return the SPD to the standby power mode.

In the write operation, upon receipt of eight bits of data the SPD will respond with an acknowledge, and await the next eight bits of data, again responding with an acknowledge until the stop condition is issued by master.

SLAVE ADDRESS ADDRESSING

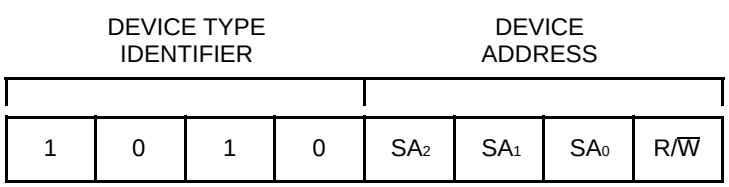
Following a start condition, the master must output the eight bits slave address. The most significant four bits of the slave address are device type identifier. For the SPD this is fixed as 1010[B]. Refer to the Fig. 2 below.

The next three significant bits are used to select a particular device. A system could have up to eight SPD devices —namely up to eight modules— on the bus. The eight addresses for eight SPD devices are defined by the state of the SA_0, SA_1 and SA_2 inputs.

The last bit of the slave address defines the operation to be performed. When R/$\overline{W}$ bit is “1”, a read operation is selected, when R/$\overline{W}$ bit is “0”, a write operation is selected.

Following the start condition, the SPD monitors the SDA line comparing the slave address being transmitted with its slave address (device type and state of SA_0, SA_1, and SA_2 inputs). Upon a correct compare the SPD outputs an acknowledge on the SDA line. Depending on the state of the R/$\overline{W}$ bit, the SPD will execute a read or write operation.

Fig. 2 – SLAVE ADDRESS

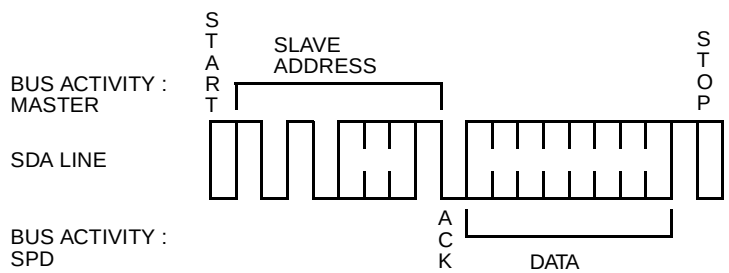


3. READ OPERATIONS

CURRENT ADDRESS READ

Internally the SPD contains an address counter that maintains the address of the last data accessed, incremented by one. Therefore, if the last access (either a read or write operation) was to address(n), the next read operation would access data from address(n+1). Upon receipt of the slave address with the R/$\overline{W}$ bit = “1”, the SPD issues an acknowledge and transmits the eight bits of data during the next eight clock cycles. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig. 3 for the sequence of address, acknowledge and data transfer.

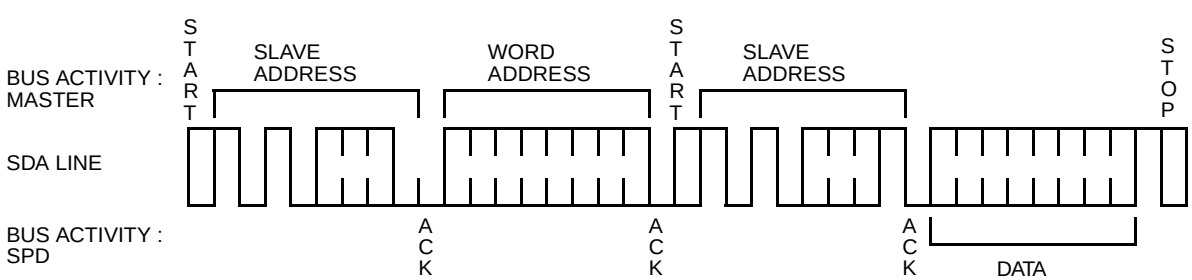
Fig. 3 – CURRENT ADDRESS READ



RANDOM READ

Random Read operations allow the master to access any memory location in a random manner. Prior to issuing the slave address with the R/$\overline{W}$ bit = “1”, the master must first perform a “dummy” write operation on the SPD. The master issues the start condition, and the slave address followed by the word address. After the word address acknowledge, the master immediately reissues the start condition and the slave address with the R/$\overline{W}$ bit = “1”. This will be followed by an acknowledge from the SPD and then by the eight bits of data. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig. 4 for the sequence of address, acknowledge and data transfer.

Fig. 4 – RANDOM READ

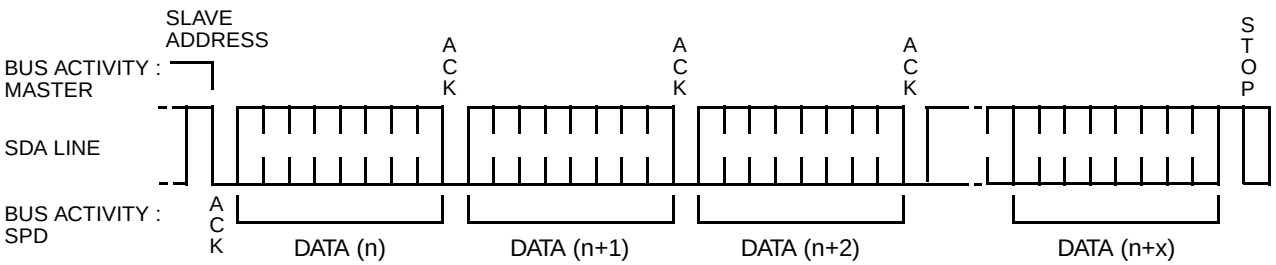


SEQUENTIAL READ

Sequential Read can be initiated as either a current address read or random read. The first data are transmitted as with the other read mode, however, the master now responds with an acknowledge, indicating it requires additional data. The SPD continues to output data for each acknowledge received. The master terminates this transmission by issuing a stop condition, omitting the ninth clock cycle acknowledge. Refer to Fig. 5 for the sequence of address, acknowledge and data transfer.

The data output is sequential, with the data from address(n) followed by the data from address(n+1). The address counter for read operations increments all address bits, allowing the entire memory contents to be serially read during one operation. At the end of the address space (address 255), the counter “rolls over” to address 0 and the SPD continues to output data for each acknowledge received.

Fig. 5 – SEQUENTIAL READ



4. DC CHARACTERISTICS

Parameter	Note	Symbol	Condition	Value		Unit
				Min.	Max.	
Input Leakage Current		S_{ILI}	$0\ V \le V_{IN} \le V_{CC}$	–10	10	µA
Output Leakage Current		S_{ILO}	$0\ V \le V_{OUT} \le V_{CC}$	–10	10	µA
Output Low Voltage	*1	S_{VOL}	I_{OL} = 3.0 mA	—	0.4	V

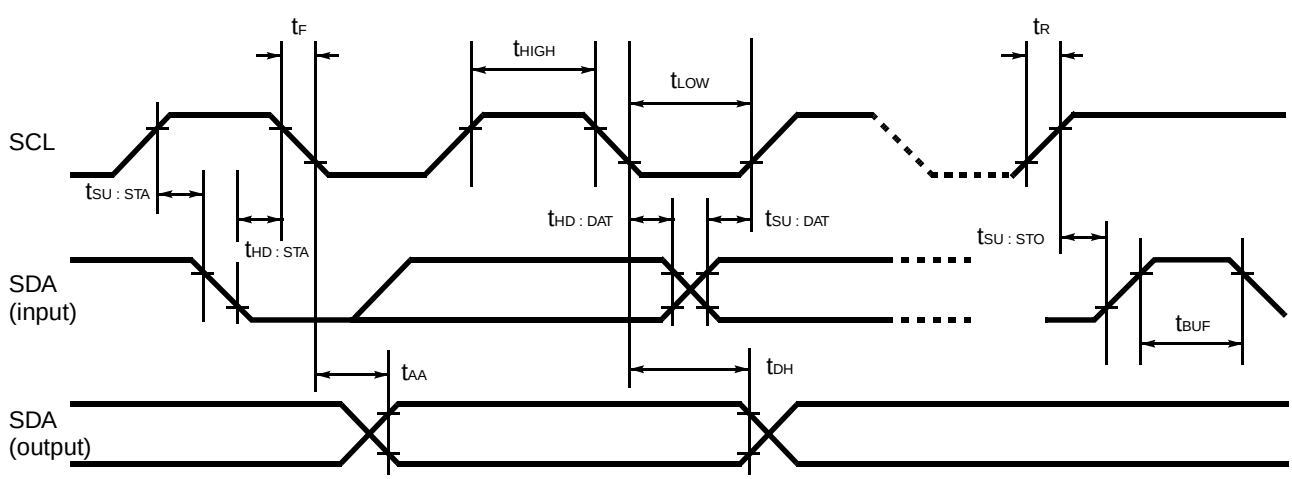
Note: *1. Referenced to V_{SS}.

MB8504S072BZ-75/-102/-10

5. AC CHARACTERISTICS

No.	Parameter	Symbol	Value		Unit
			Min.	Max.	
1	SCL Clock Frequency	f_{SCL}	—	100	KHz
2	Noise Suppression Time Constant at SCL, SDA Inputs	T_I	—	100	ns
3	SCL Low to SDA Data Out Valid	t_{AA}	—	3.5	µs
4	Time the Bus Must Be Free Before a New Transmission Can Start	t_{BUF}	4.7	—	µs
5	Start Condition Hold Time	$t_{HD:STA}$	4.0	—	µs
6	Clock Low Period	t_{LOW}	4.7	—	µs
7	Clock High Period	t_{HIGH}	4.0	—	µs
8	Start Condition Setup Time	$t_{SU:STA}$	4.7	—	µs
9	Data in Hold Time	$t_{HD:DAT}$	0	—	µs
10	Data in Setup Time	$t_{SU:DAT}$	250	—	ns
11	SDA and SCL Rise Time	t_R	—	1	µs
12	SDA and SCL Fall Time	t_F	—	300	ns
13	Stop Condition Setup Time	$t_{SU:STO}$	4.7	—	µs
14	Data Out Hold Time	t_{DH}	100	—	ns
15	Write Cycle Time	t_{WR}	—	15	ms

Fig. 6 – TIMING WAVEFORM



■ PACKAGE DIMENSION

168-pin plastic DIMM (socket type)
(MDS-168P-P27)

T.B.D.

Dimension in mm (inches)

MB8504S072BZ-75/-102/-10

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